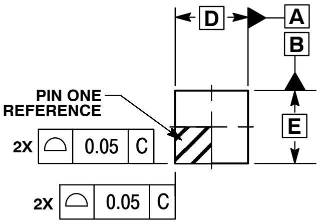
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

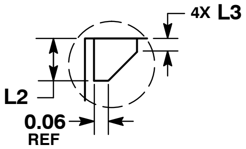
SCALE 4:1

XDFN4 0.8x0.8, 0.48P
CASE 711AB
ISSUE O

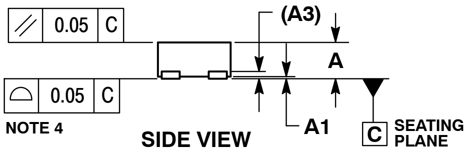
DATE 21 OCT 2010



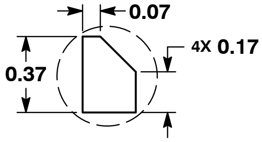
TOP VIEW



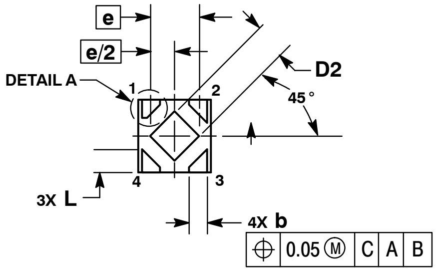
DETAIL A



SIDE VIEW

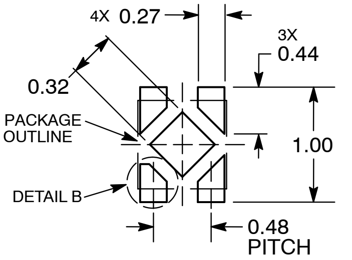


DETAIL B



BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT*



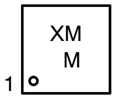
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
A3	0.10 REF	
b	0.17	0.27
D	0.80 BSC	
D2	0.20	0.30
E	0.80 BSC	
e	0.48 BSC	
L	0.23	0.33
L2	0.17	0.27
L3	0.01	0.11

GENERIC MARKING DIAGRAM*



X = Specific Device Code
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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DESCRIPTION:	**XDFN4, 0.8X0.8, 0.48P**	**PAGE 1 OF 1**